



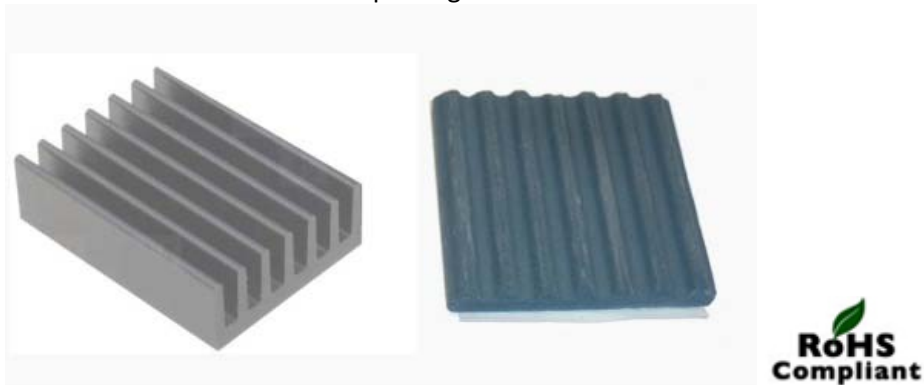
Micro Porous Ceramic Heat Sink / FCH Ceramic Series

A ceramic heat sink not only adapts to these two factors but also eases the design and applies a cooling structure of electronic products.

The entirely new material structure of a ceramic heat sink moves heat by air circulation (without external force) through the embedded radiation microporous ceramic material such that the accompanying IC components can operate continuously in a given temperature environment.

A ceramic heat sink is non-electrical conductive, humidity and dust proof by its special material nature. With a long life span and simple assembly process (simply paste it to the surface of any IC component) a ceramic heat sink saves not only assembly time but also material and labour costs.

Ceramic heat sinks are now adopted by IC of power under 10W while specially designed ones are also available for high-watt ICs. They are both ROHS and REACH compliant green material.



Dimensional Data:

Part Number	Length (mm)	Width (mm)	Height (mm)	Shape
FCH25255F7FAA	25 +/- 0.5	25 +/- 0.5	5.0 +/- 0.23	Fin
FCH30305F6FAA	30 +/- 0.5	30 +/- 0.5	5.25 +/- 0.23	Fin
FCH303512F6FAA	35 +/- 0.5	30 +/- 0.5	12.25 +/- 0.23	Fin
FCH40405F7FAA	40 +/- 0.5	40 +/- 0.5	5.25 +/- 0.23	Fin
FCH505010FAA	50 +/- 0.5	50 +/- 0.5	10.25 +/- 0.23	Fin
FCH505015F7FAA	50 +/- 0.5	50 +/- 0.5	10.25 +/- 0.23	Fin

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